

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

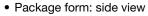
VSMB2948SL is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic package (with lens) for surface mounting (SMD).

APPLICATIONS

- · Remote control
- · IR touch panels

FEATURES

Package type: surface mount





Peak wavelength: λ_p = 940 nm

· High reliability

· High radiant power

· High radiant intensity

• Angle of half intensity: $\varphi = \pm 25^{\circ}$

· Low forward voltage

· Suitable for high pulse current operation

 Package matches with detector VEMD2023SLX01 and VEMT2023SLX01

• Floor life: 4 weeks, MSL 2a, acc. J-STD-020

 Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>



RoHS COMPLIANT GREEN (5-2008)

PRODUCT SUMMARY				
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)
VSMB2948SL	20	± 25	940	15

Note

· Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMB2948SL	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view		

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_{R}	5	V
Forward current		I _F	100	mA
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA
Power dissipation		P _V	160	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	- 40 to + 85	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	according figure 9, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W



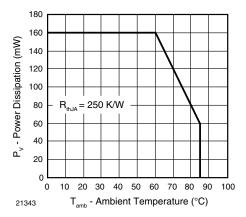


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

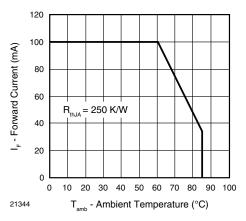


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V _F	1.15	1.35	1.6	V
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	V _F		1.8		V
Temperature coefficient of V _F	I _F = 1 mA	TK _{VF}		- 1.5		mV/K
Reverse current	V _R = 5 V	I _R			10	μΑ
Junction capacitance	$V_R = 0 \text{ V}, f = 1 \text{ MHz}, E = 0 \text{ mW/cm}^2$	CJ		21		pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	10	20	30	mW/sr
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	l _e		90		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe		40		mW
Temperature coefficient of radiant power	I _F = 1 mA	TKφ _e		- 1.1		%/K
Angle of half intensity		φ		± 25		deg
Peak wavelength	I _F = 30 mA	λ_{p}	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ		25		nm
Temperature coefficient of λ _p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		15		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		15		ns
Cut-off frequency	I _{DC} = 70 mA, I _{AC} = 30 mA pp	f _c		23		MHz

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

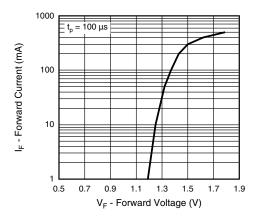


Fig. 3 - Forward Current vs. Forward Voltage

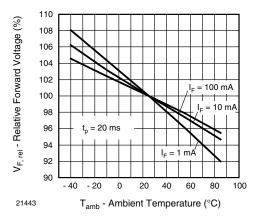


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

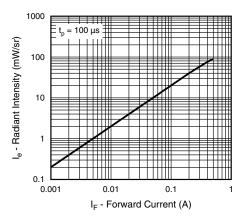


Fig. 5 - Radiant Intensity vs. Forward Current

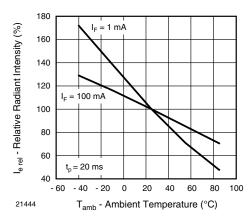


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

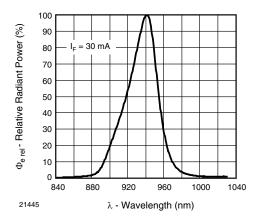


Fig. 7 - Relative Radiant Power vs. Wavelength

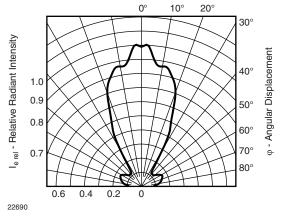


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



SOLDER PROFILE

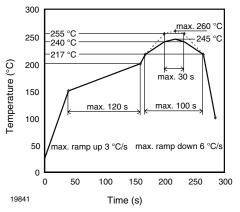


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

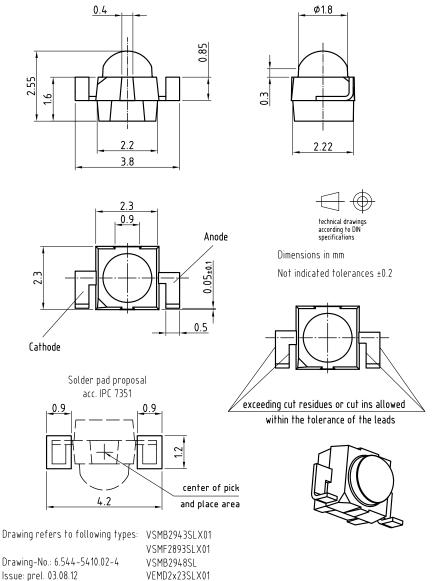
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

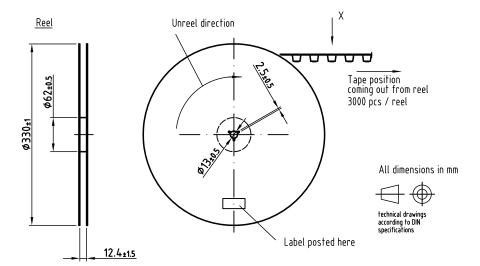
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMB2948SL

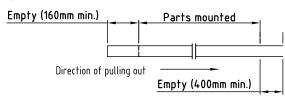




TAPING AND REEL DIMENSIONS in millimeters: VSMB2948SL

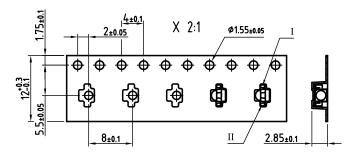


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II	
VSMB2943SLX01			
VSMF2893SLX01		١.,	
VSMB2948SL	Cathode	Anode	
VEMD2023SLX01			
VEMD2523SLX01			
VEMT2023SLX01	C.111	F-111	
VEMT2523SLX01	Collector	Emitter	
VSMY2853SL	Anode	Cathode	



Drawing refers to following types: see table Reel dimensions and tape

Drawing-No.: 9.800-5123.01-4 Issue: prel; 01.02.13

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